

L Number	Hits	Search Text	DB	Time stamp
-	645	(216/83).CCLS.	USPAT;	2003/03/21 19:39
-	252	(216/39).CCLS.	US-PGPUB	2003/03/21 19:41
-	17	((216/39).CCLS.) and (etch\$3 with hole with contact\$3)	USPAT;	2003/03/21 20:15
-	1	("5348524").PN.	US-PGPUB	2003/03/21 19:47
-	1	("5345824").PN.	USPAT;	2003/03/21 19:47
-	73	5345824.URPN.	US-PGPUB	2003/03/21 19:48
-	1	216/\$.ccls. and (etch\$3 with hole with contact\$3 with bridg\$3)	USPAT;	2003/03/22 19:53
-	5	08/028,922	US-PGPUB	2003/03/22 16:16
-	23	216/\$.ccls. and (material with conductiv\$3 with bridg\$3)	USPAT;	2003/03/23 12:38
-	1	("5427975").PN.	US-PGPUB	2003/03/22 19:58
-	5	("5461003" "5510645" "5597444" "5744399" "5750415").PN.	USPAT;	2003/03/22 20:08
-	4	216/\$.ccls. and (material with layer with (multip\$3 plural\$4) with bridg\$3)	USPAT;	2003/03/23 12:43
-	15	216/\$.ccls. and (material with (infill sacrificial) with plasma with (deposit\$3 form\$3 coat\$3))	US-PGPUB	2003/03/23 12:46
-	7	216/\$.ccls. and (material with (infill sacrificial) with ("PECVD") with (deposit\$3 form\$3 coat\$3))	USPAT;	2003/03/23 13:11
-	34	216/\$.ccls. and (polysilicon with (infill sacrificial)with material)	US-PGPUB	2003/03/23 14:13
-	56	(216/\$.ccls. 118/\$.ccls.) and (plasma with dual with frequency)	USPAT;	2003/03/23 13:41
-	1	(216/\$.ccls. 118/\$.ccls.) and ((plasma with dual with frequency) same (generat\$3 and accelerat\$3))	US-PGPUB	2003/03/23 13:44
-	2	6199505.URPN.	USPAT	2003/03/23 13:43
-	0	plasma same dual same frequency same generat\$3 and accelerat\$3	EPO; JPO; DERWENT	2003/03/23 21:07
-	0	plasma same dual same frequency same generat\$3 same accelerat\$3	EPO; JPO; DERWENT	2003/03/23 13:45
-	239726	plasma and dual and frequency and generat\$3and accelerat\$3	EPO; JPO; DERWENT	2003/03/23 13:45
-	0	plasma and dual and frequency and generat\$3 and accelerat\$3	EPO; JPO; DERWENT	2003/03/23 13:45
-	0	plasma and dual and frequency and generat\$3 and accelerat\$3	EPO; JPO; DERWENT	2003/03/23 13:45
-	30	plasma same dual same frequency same generat\$3 and accelerat\$3	USPAT;	2003/03/23 13:46
-	0	216/\$.ccls. and ((infill sacrificial) with expand\$3 with (channel groove trench))	US-PGPUB	2003/03/23 14:17
-	13	216/\$.ccls. and ((infill sacrificial) with expand\$3)	USPAT;	2003/03/23 14:14
-	10	((infill sacrificial) with expand\$3 with (chännel groove trench))	US-PGPUB	2003/03/23 14:23
-	1	((infill sacrificial) with (expand\$3 spread) with (channel groove trench))	EPO; JPO; DERWENT	2003/03/23 14:25
-	1	((infill sacrificial) with (expand\$3 spread\$3) with (channel groove trench))	EPO; JPO; DERWENT	2003/03/23 14:25
-	45	((infill sacrificial) with (expand\$3 spread\$3))	EPO; JPO; DERWENT	2003/03/23 14:30
-	182	((infill sacrificial) with (expand\$3 spread\$3))	USPAT;	2003/03/23 14:30
-	76	((infill sacrificial) with (expand\$3 spread\$3)) and (semiconductor substrate wafer)	US-PGPUB	2003/03/23 15:00
-	0	photoresist same pattern same ethh\$3	EPO; JPO; DERWENT	2003/03/23 15:00
-	7919	photoresist same pattern same etch\$3	EPO; JPO; DERWENT	2003/03/23 15:01

-	29	photoresist same pattern same etch\$3 same bridg\$3	EPO; JPO; DERWENT	2003/03/23 15:15
-	1	photoresist same pattern same etch\$3 same polyimide	EPO; JPO; DERWENT	2003/03/23 15:18
-	1	photoresist same pattern same mask same polyimide	EPO; JPO; DERWENT	2003/03/23 15:18
-	4441	photoresist with pattern with mask	EPO; JPO; DERWENT	2003/03/23 15:19
-	0	photoresist with polymide	EPO; JPO; DERWENT	2003/03/23 15:19
-	12	photoresist with polyimide	EPO; JPO; DERWENT	2003/03/23 15:30
-	18	photoresist with (sacrificial) with material	EPO; JPO; DERWENT	2003/03/23 15:38
-	0	photoresist with (infill) with material	EPO; JPO; DERWENT	2003/03/23 15:38
-	0	photoresist with (infill) with material	USPAT; US-PGPUB	2003/03/23 15:39
-	334	photoresist with (sacrificial) with material	USPAT; US-PGPUB	2003/03/23 15:39
-	47	photoresist with (sacrificial) with material with mask	USPAT; US-PGPUB	2003/03/23 15:57
-	137	photoresist with (sacrificial) with used	USPAT; US-PGPUB	2003/03/23 15:57
-	78	(trench cavity groove) with (sacrificial infill) with (photoresist)	USPAT; US-PGPUB	2003/03/23 15:58
-	12	(trench cavity groove) with (sacrificial infill) with (photoresist)	EPO; JPO; DERWENT	2003/03/23 16:01
-	1	("6096656").PN.	USPAT; US-PGPUB	2003/03/23 16:01
-	78	(trench cavity groove) with (sacrificial infill) with (photoresist)	USPAT; US-PGPUB	2003/03/23 16:02
-	11	((US-5474651-\$ or US-5364497-\$ or US-4829659-\$ or US-5345824-\$ or US-6227050-\$ or US-6149190-\$ or US-6012336-\$ or US-5798283-\$ or US-5747353-\$ or US-5640039-\$ or US-5622633-\$ or US-5620933-\$ or US-5540095-\$ or US-6525880-\$ or US-6287979-\$ or US-4289846-\$ or US-5427975-\$ or US-5510645-\$ or US-5683591-\$ or US-6402969-\$ or US-6096656-\$ or US-6174820-\$ or US-6214248-\$ or US-6242356-\$ or US-5633209-\$ or US-5738757-\$).did. or (US-5804084-\$ or US-6517735-\$ or US-6199505-\$ or US-5324553-\$ or US-6008124-\$ or US-5656123-\$ or US-5885124-\$ or US-5897343-\$ or US-5971825-\$ or US-5922515-\$ or US-6004179-\$ or US-6387819-\$ or US-5263111-\$).did. or (US-20020020689-\$ or US-20020096018-\$ or US-20020020053-\$ or US-20020160561-\$ or US-20030010745-\$).did. or (JP-02235359-\$ or JP-01057618-\$ or JP-06085337-\$).did. or (JP-2001144082-\$ or EP-592094-\$ or US-5405806-\$ or EP-805489-\$ or US-6096656-\$).did.) and (photoresist with sacrificial)	USPAT; US-PGPUB	2003/03/23 21:07
-	41	(216/\$.ccls. and (photoresist with sacrificial with material))	USPAT; US-PGPUB	2003/03/23 16:35

-	4	((US-5474651-\$ or US-5364497-\$ or US-4829659-\$ or US-5345824-\$ or US-6227050-\$ or US-6149190-\$ or US-6012336-\$ or US-5798283-\$ or US-5747353-\$ or US-5640039-\$ or US-5622633-\$ or US-5620933-\$ or US-5540095-\$ or US-6525880-\$ or US-6287979-\$ or US-4289846-\$ or US-5427975-\$ or US-5510645-\$ or US-5683591-\$ or US-6402969-\$ or US-6096656-\$ or US-6174820-\$ or US-6214248-\$ or US-6242356-\$ or US-5633209-\$ or US-5738757-\$).did. or (US-5804084-\$ or US-6517735-\$ or US-6199505-\$ or US-5324553-\$ or US-6008124-\$ or US-5656123-\$ or US-5885124-\$ or US-5897343-\$ or US-5971825-\$ or US-5922515-\$ or US-6004179-\$ or US-6387819-\$ or US-5263111-\$ or US-5830773-\$ or US-5275973-\$ or US-5547093-\$ or US-5820771-\$ or US-5824186-\$).did. or (US-20020020689-\$ or US-20020096018-\$ or US-20020020053-\$ or US-20020160561-\$ or US-20030010745-\$).did. or (JP-02235359-\$ or JP-01057618-\$ or JP-06085337-\$).did. or (JP-2001144082-\$ or EP-592094-\$ or US-5405806-\$ or EP-805489-\$ or US-6096656-\$).did.) and (photoresist with mask with pattern)	USPAT; US-PGPUB	2003/03/23 16:55
-	18	((US-5474651-\$ or US-5364497-\$ or US-4829659-\$ or US-5345824-\$ or US-6227050-\$ or US-6149190-\$ or US-6012336-\$ or US-5798283-\$ or US-5747353-\$ or US-5640039-\$ or US-5622633-\$ or US-5620933-\$ or US-5540095-\$ or US-6525880-\$ or US-6287979-\$ or US-4289846-\$ or US-5427975-\$ or US-5510645-\$ or US-5683591-\$ or US-6402969-\$ or US-6096656-\$ or US-6174820-\$ or US-6214248-\$ or US-6242356-\$ or US-5633209-\$ or US-5738757-\$).did. or (US-5804084-\$ or US-6517735-\$ or US-6199505-\$ or US-5324553-\$ or US-6008124-\$ or US-5656123-\$ or US-5885124-\$ or US-5897343-\$ or US-5971825-\$ or US-5922515-\$ or US-6004179-\$ or US-6387819-\$ or US-5263111-\$ or US-5830773-\$ or US-5275973-\$ or US-5547093-\$ or US-5820771-\$ or US-5824186-\$).did. or (US-20020020689-\$ or US-20020096018-\$ or US-20020020053-\$ or US-20020160561-\$ or US-20030010745-\$).did. or (JP-02235359-\$ or JP-01057618-\$ or JP-06085337-\$).did. or (JP-2001144082-\$ or EP-592094-\$ or US-5405806-\$ or EP-805489-\$ or US-6096656-\$).did.) and (photoresist with mask)	USPAT; US-PGPUB	2003/03/23 16:55

-	17	((US-5474651-\$ or US-5364497-\$ or US-4829659-\$ or US-5345824-\$ or US-6227050-\$ or US-6149190-\$ or US-6012336-\$ or US-5798283-\$ or US-5747353-\$ or US-5640039-\$ or US-5622633-\$ or US-5620933-\$ or US-5540095-\$ or US-6525880-\$ or US-6287979-\$ or US-4289846-\$ or US-5427975-\$ or US-5510645-\$ or US-5683591-\$ or US-6402969-\$ or US-6096656-\$ or US-6174820-\$ or US-6214248-\$ or US-6242356-\$ or US-5633209-\$ or US-5738757-\$).did. or (US-5804084-\$ or US-6517735-\$ or US-6199505-\$ or US-5324553-\$ or US-6008124-\$ or US-5656123-\$ or US-5885124-\$ or US-5897343-\$ or US-5971825-\$ or US-5922515-\$ or US-6004179-\$ or US-6387819-\$ or US-5263111-\$ or US-5830773-\$ or US-5275973-\$ or US-5547093-\$ or US-5820771-\$ or US-5824186-\$).did. or (US-20020020689-\$ or US-20020096018-\$ or US-20020020053-\$ or US-20020160561-\$ or US-20030010745-\$).did. or (JP-02235359-\$ or JP-01057618-\$ or JP-06085337-\$).did. or (JP-2001144082-\$ or EP-592094-\$ or US-5405806-\$ or EP-805489-\$ or US-6096656-\$).did.) and ((plasma or "PECVD") with (sacrificial infill))	USPAT; US-PGPUB; JPO; DERWENT	2003/03/23 19:16
-	5	216/\$.ccls. and (bridg\$3 with material with electric\$3 with conductiv\$3)	USPAT; US-PGPUB; JPO; DERWENT	2003/03/23 19:17